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Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China







# **Zener Voltage Regulators**

### 500 mW SOD-123 Surface Mount

Three complete series of Zener diodes are offered in the convenient, surface mount plastic SOD-123 package. These devices provide a convenient alternative to the leadless 34-package style.

### **Features**

- 500 mW Rating on FR-4 or FR-5 Board
- Wide Zener Reverse Voltage Range 1.8 V to 43 V
- Package Designed for Optimal Automated Board Assembly
- Small Package Size for High Density Applications
- ESD Rating of Class 3 (> 16 kV) per Human Body Model
- SZ Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- Pb-Free Packages are Available\*

### **Mechanical Characteristics:**

CASE: Void-free, transfer-molded, thermosetting plastic case

FINISH: Corrosion resistant finish, easily solderable

### **MAXIMUM CASE TEMPERATURE FOR SOLDERING PURPOSES:**

260°C for 10 Seconds

**POLARITY:** Cathode indicated by polarity band

FLAMMABILITY RATING: UL 94 V-0

### **MAXIMUM RATINGS**

Rating	Symbol	Max	Units
Total Power Dissipation on FR-5 Board, (Note 1) @ T <sub>L</sub> = 75°C Derated above 75°C	P <sub>D</sub>	500 6.7	mW mW/°C
Thermal Resistance, (Note 2) Junction-to-Ambient	$R_{\theta JA}$	340	°C/W
Thermal Resistance, (Note 2) Junction-to-Lead	$R_{ heta JL}$	150	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- 1.  $FR-5 = 3.5 \times 1.5$  inches, using the minimum recommended footprint.
- 2. Thermal Resistance measurement obtained via infrared Scan Method.

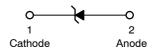


### ON Semiconductor®

http://onsemi.com



SOD-123 CASE 425 STYLE 1



### **MARKING DIAGRAM**



xx = Device Code (Refer to page 3)

M = Date Code= Pb-Free Package

(Note: Microdot may be in either location)

### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MMSZ4xxxT1G	SOD-123 (Pb-Free)	3,000 / Tape & Reel
SZMMSZ4xxxT1G	SOD-123 (Pb-Free)	3,000 / Tape & Reel
MMSZ4xxxT3G	SOD-123 (Pb-Free)	10,000 / Tape & Reel
SZMMSZ4xxxT3G	SOD-123 (Pb-Free)	10,000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

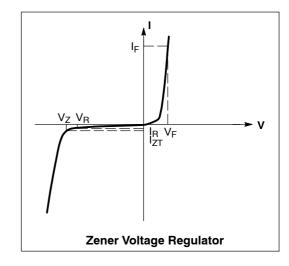
### **DEVICE MARKING INFORMATION**

See specific marking information in the device marking column of the Electrical Characteristics table on page 3 of this data sheet.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted, $V_F = 0.95$ V Max. @ $I_F = 10$ mA)

Symbol	Parameter
VZ	Reverse Zener Voltage @ I <sub>ZT</sub>
I <sub>ZT</sub>	Reverse Current
I <sub>R</sub>	Reverse Leakage Current @ V <sub>R</sub>
$V_{R}$	Reverse Voltage
Ιϝ	Forward Current
V <sub>F</sub>	Forward Voltage @ I <sub>F</sub>



**ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$  unless otherwise noted,  $V_F = 0.9 \text{ V Max.}$  @  $I_F = 10 \text{ mA}$ )

			Zener Voltage (Note 3)				Leakage Current	
	Device		V <sub>Z</sub> (Volts)			I <sub>R</sub> @	<sub>R</sub> @ V <sub>R</sub>	
Device*	Marking	Min	Nom	Max	μΑ	μА	Volts	
MMSZ4678T1G	CC	1.71	1.8	1.89	50	7.5	1	
MMSZ4679T1G	CD	1.90	2.0	2.10	50	5	1	
MMSZ4680T1G	CE	2.09	2.2	2.31	50	4	1	
MMSZ4681T1G	CF	2.28	2.4	2.52	50	2	1	
MMSZ4682T1G	CH	2.565	2.7	2.835	50	1	1	
MMSZ4683T1G	CJ	2.85	3.0	3.15	50	0.8	1	
MMSZ4684T1G	СК	3.13	3.3	3.47	50	7.5	1.5	
MMSZ4685T1G	СМ	3.42	3.6	3.78	50	7.5	2	
MMSZ4686T1G	CN	3.70	3.9	4.10	50	5	2	
MMSZ4687T1G	CP	4.09	4.3	4.52	50	4	2	
MMSZ4688T1G	СТ	4.47	4.7	4.94	50	10	3	
MMSZ4689T1G	CU	4.85	5.1	5.36	50	10	3	
MMSZ4690T1G/T3G	CV	5.32	5.6	5.88	50	10	4	
MMSZ4691T1G	CA	5.89	6.2	6.51	50	10	5	
MMSZ4692T1G	CX	6.46	6.8	7.14	50	10	5.1	
MMSZ4693T1G	CY	7.13	7.5	7.88	50	10	5.7	
MMSZ4694T1G	CZ	7.79	8.2	8.61	50	1	6.2	
MMSZ4695T1G	DC	8.27	8.7	9.14	50	1	6.6	
MMSZ4696T1G	DD	8.65	9.1	9.56	50	1	6.9	
MMSZ4697T1G	DE	9.50	10	10.50	50	1	7.6	
MMSZ4698T1G	DF	10.45	11	11.55	50	0.05	8.4	
MMSZ4699T1G	DH	11.40	12	12.60	50	0.05	9.1	
MMSZ4700T1G	DJ	12.35	13	13.65	50	0.05	9.8	
MMSZ4701T1G	DK	13.30	14	14.70	50	0.05	10.6	
MMSZ4702T1G	DM	14.25	15	15.75	50	0.05	11.4	
MMSZ4703T1G <sup>†</sup>	DN	15.20	16	16.80	50	0.05	12.1	
MMSZ4704T1G	DP	16.15	17	17.85	50	0.05	12.9	
MMSZ4705T1G	DT	17.10	18	18.90	50	0.05	13.6	
MMSZ4706T1G	DU	18.05	19	19.95	50	0.05	14.4	
MMSZ4707T1G	DV	19.00	20	21.00	50	0.01	15.2	
MMSZ4708T1G	DA	20.90	22	23.10	50	0.01	16.7	
MMSZ4709T1G	DX	22.80	24	25.20	50	0.01	18.2	
MMSZ4710T1G	DY	23.75	25	26.25	50	0.01	19.0	
MMSZ4711T1G <sup>†</sup>	EA	25.65	27	28.35	50	0.01	20.4	
MMSZ4712T1G	EC	26.60	28	29.40	50	0.01	21.2	
MMSZ4713T1G	ED	28.50	30	31.50	50	0.01	22.8	
MMSZ4714T1G	EE	31.35	33	34.65	50	0.01	25.0	
MMSZ4715T1G	EF	34.20	36	37.80	50	0.01	27.3	
MMSZ4716T1G	EH	37.05	39	40.95	50	0.01	29.6	
MMSZ4717T1G	EJ	40.85	43	45.15	50	0.01	32.6	

<sup>3.</sup> Nominal Zener voltage is measured with the device junction in thermal equilibrium at  $T_L = 30^{\circ}C \pm 1^{\circ}C$ .

<sup>\*</sup>Include SZ-prefix devices where applicable. †MMSZ4703 and MMSZ4711 Not Available in 10,000/Tape & Reel

### **TYPICAL CHARACTERISTICS**

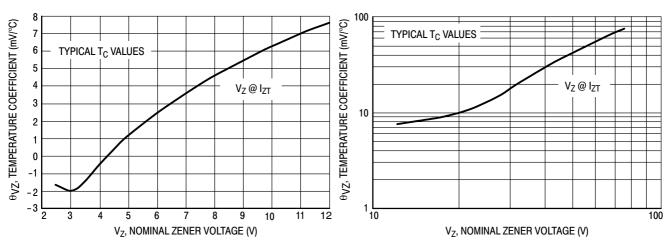


Figure 1. Temperature Coefficients (Temperature Range – 55°C to +150°C)

Figure 2. Temperature Coefficients (Temperature Range – 55°C to +150°C)

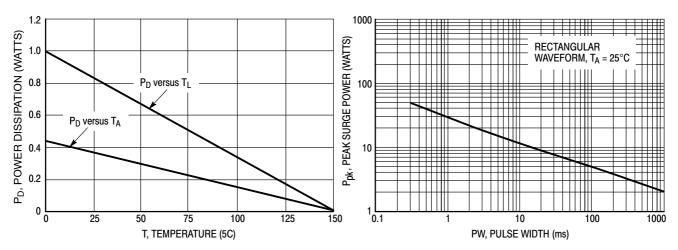


Figure 3. Steady State Power Derating

Figure 4. Maximum Nonrepetitive Surge Power

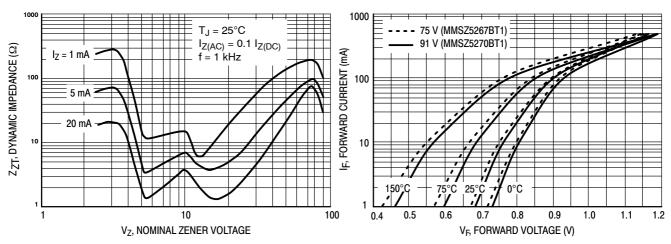


Figure 5. Effect of Zener Voltage on Zener Impedance

Figure 6. Typical Forward Voltage

### **TYPICAL CHARACTERISTICS**

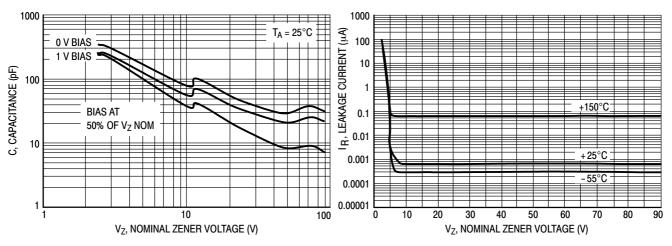


Figure 7. Typical Capacitance

Figure 8. Typical Leakage Current

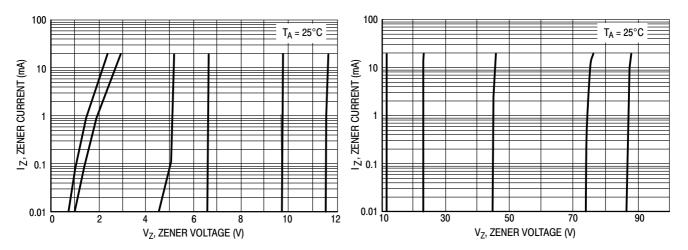
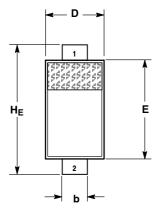


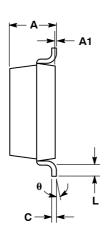
Figure 9. Zener Voltage versus Zener Current (V<sub>Z</sub> Up to 12 V)

Figure 10. Zener Voltage versus Zener Current (12 V to 91 V)

### PACKAGE DIMENSIONS

SOD-123 CASE 425-04 ISSUE G





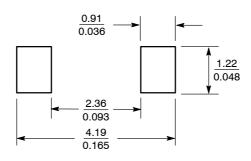
#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
  - Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.94	1.17	1.35	0.037	0.046	0.053
A1	0.00	0.05	0.10	0.000	0.002	0.004
b	0.51	0.61	0.71	0.020	0.024	0.028
С			0.15			0.006
D	1.40	1.60	1.80	0.055	0.063	0.071
E	2.54	2.69	2.84	0.100	0.106	0.112
HE	3.56	3.68	3.86	0.140	0.145	0.152
L	0.25			0.010		
θ	0°		10°	0°		10°

STYLE 1: PIN 1. CATHODE 2. ANODE

### **SOLDERING FOOTPRINT\***



SCALE 10:1  $\left(\frac{\text{mm}}{\text{inches}}\right)$ 

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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